

Index

- 2D-light-section sensor, 299–301
- 3D-light-section sensor, 301–302
- 16MnCr5, 307, 308, 309
- III/V compound semiconductors, 7

- ABCD matrix, 186
- Aberration, 194
- Absorptance, 427
- Absorption, 287, 338, 389, 391, 394, 427,
449, 469, 493
 - of aluminum, 304
 - of polymers, 363, 364, 370, 375, 376
 - of steel, 303–304
- Absorption coefficient, 378
- Absorptivity, 390, 391, 403
- Acceleration factor, 53
- Accessibility, 330
- Accuracy, 388
- Activation energy, 86
- Additives, 363, 375
- Aeronautical applications, 333–334
- Air knife, 291, 418
- Alloying, 432, 456, 482, 483
 - elements, 287
- AlMg5, 397
- Aluminum, 304, 305, 313, 322–323, 324,
339, 391, 397
 - alloys, 321, 322
 - fittings, 333
- Aluminum oxide, 105
- Amorphous thermoplastics, 376
- Angle of incidence, 318, 319, 391, 428,
496, 517
- Annealing, 426, 434, 459, 470, 481
- Annular diode laser beam, 268–272,
314–315, 320, 388, 406, 407, 408,
409, 412
- Anti-reflection coating, 61, 66
- Aperture filling, 149
- Argon, 310, 312, 453
- Arrhenius relationship, 207
- Aspect ratio, 288, 289, 306, 307, 308, 309,
312, 315
- Assist gas jet, 389, 391, 393–394
- Assist gas pressure, 393
- Astigmatism, 58–59, 67–68, 190–195, 233
 - measurement, 59, 233
- Atmospheric plasma spraying (APS),
503, 522
- AuSn, 80, 95
- Austenite, 314
- Autogenous cutting, 405, 406, 408, 409,
410, 411
 - cutting speeds, 406
- Automotive applications, 324–333
- Axial annular welds, 321
- Axle carrier, 330

- Ball grid arrays. *See* BGA
- Band gap, 5–10
- Band material, 400
- Band-pass filter, 146
- Band-stop filter, 146
- Band structure, 6, 7, 10, 43
- Band tension, 401–405
- Batch process, 79
- Bead-on-plate welding, 303–306
- Beam caustic, 200
- Beam characteristics, 181
- Beam-director, 168
- Beam divergence angle, 37
- Beam-guiding system, 399
- Beam homogenization, 400
- Beam intensity, 389, 416
- Beam intensity distribution, 310
- Beam parameter product (BPP), 121, 159,
166, 175, 181, 193, 389, 391, 393
- Beam patterns, 405
- Beam positional stability, 204–205
- Beam propagation, 183–186, 379, 394
- Beam propagation parameter (M^2), 56, 65,
66, 67
- Beam propagation ratio (M^2), 182, 193,
196, 203–204
- Beam properties, 394
- Beam quality, 63–66, 121, 152–153, 388,
389, 391, 409, 416

- Beam radius, 122
- Beam shaping, 162, 386
- Beam splitter, 145
- Beam-splitter cubes, 142
- Beam symmetrization, 162
- Beam width, 182
- Bearing cross section, 318
- Bending radius, 418
- Beryllia (BeO), 105, 357
- BGAs (ball grid arrays), 355, 356
- Biological contamination, 101
- Birefringent crystals, 142
- Boundary feeding rates (BFR), 304
- Boundary layer, 406
- Brazing, 285, 342, 343, 344, 345, 346, 347–349
 - alloys, 346–347
 - filler, 342, 343, 344, 348
 - head, 345
 - seam, 346–347
 - system, 347
 - velocity, 346
- Bridged gap, 383
- Bridge formation, 343
- Brightness, 56, 63–66, 67, 122, 182
- Broad area emitters and arrays, 47–55
- Broad area lasers, 15
- Bumps, 355, 356
- Burning front, 406
- Burning proportion, 406
- Burnoff-stabilization, 412
- Burnoff-stabilized cutting, 411
- Burnoff-stabilized laser beam oxygen cutting, 405, 407, 409, 410
- Burr, 398, 404
 - formation, 393, 398
- Burst pressure, 374, 383, 384, 385
- Butt joint, 322, 323, 363, 364
- “By-emitter” analysis, 41–45

- Camera systems, 196–197
- CAN-bus, 256, 276
- Car body, 328
- Carbon black concentration (cbc), 378, 383, 385
- Catastrophic optical mirror damage (COMD), 48, 56, 206
- Ceramics, 389, 413, 425
 - materials, 425
- Characteristic temperature, 19
- Chip formation, 413, 419
- Chip section, 421
- Circular spot welds, 320
- Cladding, 427, 482, 483
- Cladding rate, 527
- Cladding with wire, 488
- Clamping, 345
 - device, 363–364
 - wheels, 294, 295
- CO₂, 313
- CO₂ laser, 326, 332, 370, 388, 399, 407, 409, 410, 411
- Coating, 346–347, 482, 499, 508, 522
- Coaxial shielding gas nozzle, 293, 294
- Cobalt-based alloys, 413, 423, 425
- Coefficient of thermal expansion (CTE), 104, 107
- Coherence, 183, 194
- Coherent coupling, 175–177
- Coil material, 388
- Cold forming tool steels, 419
- Collimation lens, 130, 136
- Collision, 330
- Color additives, 376
- Combustion, 406
- Complex optical index, 57
- Composites, 413
- Compressively strained, 10, 11
- Conduction band, 6
- Conduction cooling, 87–92
- Confinement factor, 13, 64
- Conical nozzle, 407
- Connection length, 318, 319, 346
- Constructional laser-adapted design of joining partners, 374
- Contact conditions, 415
- Contact sensors, 297
- Contour cuts, 396, 398, 399, 410, 411
- Contour welding, 365–366, 371, 382–383, 385, 387
- Convection-cooled heat sinks, 94, 95, 96
- Conventional finishing, 423
- Conventional machining, 412
- Conventional milling, 423
- Conversion efficiency, 18
- Cooling fluid, 96
- Copper, 337, 390
- Corrected far-field, 58–59, 67–68
- Corrosion, 98, 99
- Costs, 336, 399, 400
- Cotton fabric, 396, 397, 398
- Crack, 471, 504, 520, 525
- Cross member, 331
- Cross section, 307, 308, 311, 312, 315, 316, 322, 323, 326, 339, 346–349, 404, 405

- Cross-jet, 291, 292
 - nozzle, 291, 292, 407
- Cross-talk, 253
- Crystalline growth, 26
- Crystalline quality, 27
- Crystalline thermoplastics, 376
- Crystallinity, 375
- CTE matching, 102
- CTE measurement, 114
- CuAl₅Ni₂, 346–347
- CuSi₃, 346–347
- Cut edge, 389, 398, 403, 404, 406, 410, 411, 412
 - roughness, 407
- Cut geometry, 388
- Cut kerf, 389, 411
 - width, 398, 407, 410
- Cut quality, 410
- Cutting, 387, 390, 391
 - depth, 423
 - force, 419
 - front, 390, 391, 406
 - gas jet, 394
 - head, 391, 393
 - length, 401
 - model, 394
 - nozzle, 393, 406, 407
 - process, 388
 - speed, 388, 390, 393, 394, 407, 410, 413, 420, 421, 425
 - time, 401, 402, 403, 422
 - track, 401
- Cutting-to-length, 388
- CVD diamond, 102

- Decomposition, 384
 - temperature, 371, 376
- Deep-penetration welding, 286, 288, 289, 290, 312, 315, 324, 326, 340–341
- Defocusing, 322
- Degradation, 54, 63, 80, 86, 132, 163, 164, 170, 206, 207
 - mechanism, 86
 - process, 86
- Degree of absorption, 338, 363
- Degree of crystallinity, 376
- Degree of reflection, 363
- Dendrite formation, 289
- Dendrites, 308
- Deposition, 482, 503
 - of dielectrics, 29–31
- Depth of cut, 420, 421, 424
- Design aspects, 48
- Design parameters, 49
- Determination, of optical properties, 378
- DI (de-ionized) water, 100
- Diamond, 106
- Diamond heat spreaders, 101–104
- Diamond substrate, 113
- Difficult to machine materials, 424, 425
- Diffraction, 194
- Diffusion, 406
- Dilution, 489, 490, 527
- Diode laser cutting plotter, 392
- Diode lasers, 1, 10, 122, 125, 127, 128–130, 136, 142, 206, 209–210
 - application, 285, 537
 - bars, packaging of, 75, 150
 - beam quality, 162–177
 - broad area emitters and arrays, 47–55
 - chip characterization
 - methods/measurements, 33–47
 - high-brightness emitters and arrays, 55–70
 - homogeneization, of high power diode-lasers, 138–141
 - manufacturing technology, 25–33
 - principles, of operation, 5
 - stacking, 147–162
 - system, 215, 388
- Direct application, 417
- Direct integration, 418
- Distortion, 290, 328, 329, 340, 341, 342
- Distributed-feedback (DFB) lasers, 56
- Divergence angle, 38, 40, 129–133
- Double-wheel system, 294–295
- Dyes, 375

- Economic efficiency, 399
- Edge-tracking sensors, 296, 299–302
- Effective thermal conductivity, 107
- Efficiency, 34
- Efficiency model, 19
- Electric characteristics, of diode lasers, 49–53
- Electric field, 183
- Electric steel, 396, 397, 398, 401, 402, 403, 404
- Electrochemical corrosion, 100–101
- Electroluminescence, 43
- Electro-luminescence spectroscopy, 112
- Electromigration, 80
- Electronic packaging, 349
- Electro-optical characterization, 34–37, 61–63
- Emission spectrum, 50–51

- Energy bands, 5, 111
- Energy input per unit length, 377, 383, 384, 420
- Epitaxy, 26
- Erosion, 99
- Etching, 29
- Evaporation, 288, 390
- Excessive melting, 408
- Exothermal reaction, 388, 391
- Expansion-matching, 102, 104, 105, 106, 117

- Fabry–Perot resonators, 16
- Facet reflectivity, 66
- Far-field, 14, 37–40, 52, 59, 130, 193, 194, 266
 - astigmatism, 58–59, 67–69
 - corrected, 58, 67–68
 - divergence angle, 122
 - intensity distribution, 37, 39, 138–141, 176
 - measurement, 37, 201
 - power density distribution, 187, 201
- Fast-axis, 37, 53, 306, 309, 316, 318, 323
- Fast axis collimation, 128–131
- Ferrite, 313
- Fiber coupling, 152, 162, 325, 331, 332–333, 334–335, 388, 417, 418
- Fiber-reinforced
 - ceramics, 423
 - metals, 413
 - polymers, 251, 362
- Filamentation, 57
- Filler metal, 345
- Fillet weld, 320, 328, 329, 330, 346
 - at lap joint, 318, 319
- Filling factor, 123, 136, 137, 147–149, 227, 252, 257, 279
- Five-axes milling, 415
- Five-axes machining, 416
- Fixed costs, 399
- Flame cutting, 272, 405, 412
- Flame hardening, 426, 433
- Flame retardants, 376
- Flexible beam guiding, 405
- Flexprints, 355
- Flip-chips, 355, 356
- Flow rate, 98, 311
- Flux, 358
- F-number, 392, 393, 409
- Focal diameter, 335, 353, 389, 392, 409
- Focal length, 37, 131, 136, 149, 163, 305, 306, 328, 331, 393, 407
- Focal position, 310, 316, 317, 393
- Focal spot position, 420
- Focusability, 388
- Focusing, 400
- Focusing optics, 392, 408
- “Foot point,” 310
- Force/elongation diagram, 360
- Forming tools, 479, 503, 509, 510
- Free-form surfaces, 415
- Fresnel absorption, 391
- Frictional heat, 421
- F-Theta lens, 353, 367
- Full penetration, 315, 316, 317
- Fume, 291
- Fusing time, 403
- Fusion cutting, 389

- Galvanization, 328, 329
- Galvanized steel, 333
- Galvanometer scanner, 353
- Galvanometric scanning mirrors, 367
- Gap, 326, 345, 377
- Gap bridging, 316, 320, 322–323, 331, 372, 377, 378
 - capabilities, 383, 385
- Gap width, 323
- Gas foot point, 311, 312
- Gas jet, 407, 408
- Gas nozzle, 311
- Gas pressure, 391, 407
- Gaussian beam, 181, 187, 193
 - profile, 273
- General astigmatic, 190
- Glass, 399
- Glass fiber concentration, 379
- Grade of crystallisation, 379
- Graphical user interface, 272, 278
- Graphite, 389
- Guiding rails, 459

- Handling system, 391, 399
- Hardening, 425
- Hardness, 313
 - gradient, 423
 - profile, 313, 314
- Hartmann sensor, 205
- Heat-affected zone, 313, 314
- Heat capacity, 390
- Heat conduction, 87, 304, 394, 406
 - equation, 338
 - losses, 390, 395
 - welding, 286, 288, 321, 324, 333, 334, 338, 339

- Heat conductivity, 338, 390
 - of polymers, 376
- Heating, 390, 403, 413, 419
- Heat load, 389
- Heat radiation, 371, 374
- Heat sink, 19–24, 61–69, 79–82, 87–91, 94–105, 150
- Heat source, 338, 341, 406, 412, 413
- Heat spreading, 88, 106
- Heat transfer coefficient, 88, 89, 90, 92
- Height profile, 300
- Helium, 310, 312, 322
- Hem flange, 342, 343
- High carbon steel, 335
- High-brightness, 55
 - arrays, 69–70
 - emitters, 55
 - systems, 233–245
- High-power laser diode. *See* Diode lasers
- High-strength steel, 313, 315
- High-temperature-resistant steel, 412
- Holmium-YAG laser, 370
- Holographic interferometry, 107
- Homogeneity, 34
 - Beam quality, 236, 265, 269, 275, 374, 410
 - intensity, 162, 164, 235, 262
 - powder stream, 487
 - wavelength, 41, 50
 - waver growth, 26, 27
- Homogenization, 138–141, 164, 266
- Homogenizer, 262
- Hot forming tool steels, 419
- Hot machining, 413
- Hot-melt adhesive, 381–382
- Hot-zinc-dipped mild steel, 398
- Hybrid, 487
- Hybrid circuits, 357
- Hybrid process, 405
 - LAAPS, 512
- Ignition temperature, 391, 406, 408
- Image processing, 352, 374
 - with IR-camera, 373
- Incidence angle, 345
- Inclination angle, 345
- Incoherent beam superposition
 - basics, 125–128
 - collimation, 128–141
 - combination techniques, 142–149
 - quality, 121–125, 175–177
 - stacking techniques, 150–162
 - symmetrization and fiber coupling, 162–174
- Indium, 80, 103
- Indium solder, 112
- Induction, 473
 - hardening, 433, 472, 480
- Industrial applications, 387, 400
- Inert gas cutting, 389, 393–394
- Inert gas jet, 389
- Inert gas nozzle, 345
- Influence of geometry, 380
- Injection, 483
- Injection valve, 334, 467
- Integrating sphere, 34
- Intensities, 389
- Intensity distribution, 374, 379
- Interaction zone, 390
- Internal loss, 17
- International standards, 121, 122, 181–183, 203, 204, 210–211
 - IEC 60825-1, 209
 - ISO 306, 380
 - ISO 11146, 64, 67, 130, 211, 212
 - ISO 17526, 206
- Intrinsic general astigmatic, 191
- Intrinsic optical parameters, 22
- Ion-assisted-deposition (IAD), 144
- Ion beam sputtering (IBS), 144
- IR-camera, 352, 374
- Iron, 406, 432, 501
- Iron combustion, 406, 407
- Iron oxide, 406
- Irradiation time, 321, 360
- Joining of plastic to metal, 381
- Joining technologies, 285, 286
- Joint gap, 344
- Joint geometries, 363
- Joint interface, 318
- Joints, 323
- Joint tracking, 300
- Kerf cross section, 390
- Kerf volume, 390, 394, 406
- Kerf width, 389, 390, 406
- Keyhole, 289
- Kramers–Kronig relation, 15
- Lap joint, 324, 330, 326, 336
- Large optical cavity (LOC), 14, 48
- Large-scale production, 27

- Laser-assisted atmospheric plasma spraying (LAAPS), 488, 512
- Laser-assisted machining, 278, 283, 388, 413, 416, 419, 421, 423, 425
 - of metallic materials, 423
- Laser-assisted milling, 413, 414, 416, 420, 421, 425
 - of steel, 424
 - of Stellites, 425
- Laser-assisted roughing, 423
- Laser-assisted turning, 413, 423
- Laser beam oxygen cutting, 405, 406, 411
- Laser beam soldering, 349, 359, 360
- Laser beam welding, of thermoplastics, 361, 362, 386, 387
- Laser brazing, 342
- Laser cutting, 389, 392
- Laser cutting systems, 388
- Laser fusion cutting, 390
- Laser hardening, 272, 426, 427
- Laser light pattern, 290
- Laser operation, principle of, 5–25
- Laser power, 306, 391, 395, 396, 397, 408, 409, 421, 422
 - at workpiece, 394
- Laser processing, 27–31
- Laser protective window, 418
- Laser punching, 401, 405
- Laser reflection polarimetry, 109, 115
- Laser soldering system, 353
- Laser-spot orientation, 316
- Laser spot position, 320
- Laser triangulation, 298
- Laser vaporization cutting, 390
- Laser wavelength, 391
- Laser welding, 286
- Latent heat, 389, 390
- Lateral waveguide, 15–16
- Laval nozzle, 272, 407, 409
- Leading nozzle, 311
- Leather, 396, 397, 398
- Length of cut, 422
- Lifetime, 53–55, 63, 86, 98–101, 206–209
- Light pipe, 139
- Linear guiding rails, 436, 459–467
- Linear optical systems, 185–186
- Linear polarization, 396
- Line current density, 21
- Line series resistance, 22
- Line-shaped laser beam, 350, 400
- Linewidth enhancement factor, 57, 58
- Longitudinal mode, 16
- Long-term stability, 204
- Losses, 48
- Machine tool, 414
 - design, 416
- Machining, 388, 413
 - properties, 413
 - strategies, 423
 - time, 424, 425
 - zone, 414
- Manufacturing technology, of semiconductor laser, 25–33
- Marangoni effect, 313
- Martensite, 313, 314, 474, 501
- Martensitic structure, 432
- Mask welding, 366–367
- Mass density, 390
- Material, 388
 - gain, 11
 - parameter, 49
 - removal, 389
 - removal rate, 412, 421, 424
 - strength, 388, 413
 - thickness, 390
- Maximum cutting speed, 393, 394, 395, 396, 397, 408, 410
- Maximum permissible exposure, 209
- Maximum welding depth, 287
- Maxwell equations, 183
- Mean-time-to-failure (MTTF), 86
- Mechanical processes, 405
- Medium-term stability, 204
- Melt, 324, 389
- Melt burr, 381
- Melt ejection, 393, 394
- Melt flow, 394
- Melt front, 403
- Melting, 376, 388, 390, 394, 402
- Melting point, 324, 338
 - of solder for heat sink, 77, 95, 102
- Melting temperature, 380, 390, 403
- Melting volume, 403
- Melt pool, 286, 287, 288–289
- Metal cutting, 388
- Metallization, 31
- Metrology, 181–212
- Microchannel cooler, 150
- Microchannel heat sinks, 94–101
- Micro-lenses, 131
- Micro-optic mounting, 155–158
- Micro-optics, 117–118
- Microstructure, 313, 314, 434, 484, 499, 517

- Microtome cuts, 363, 377, 383, 384, 386
- Micro-welding, 336–338
- Mild steel, 288, 304, 305, 306, 314, 320, 328, 339, 388, 393, 394, 396, 397, 398, 405, 406, 408, 409, 410, 411
- Milling machine, 414
- Milling path, 422
- Milling tool, 415, 419, 420, 422
- Mirror coating, 31–32
- Mobile cladding system, 509
- Modal optical gain, 10
- Modular hardening system, 272, 448
- Modular setup, 245
- Moiré fringe analysis, 107
- MOPAs (master-oscillator power amplifiers), 56
- Morphous polymers, 379
- Mounting process, 77, 102
- Moving knife-edge, 197
- Moving pinhole, 198–200
- Moving slit, 197
- Multi-reflection, 289
- Mutual coherence, 183–184

- Nd:YAG laser, 326, 330, 332–333, 334–335, 370, 388, 399
- Near-field profile, 59, 65
- Near-net-shape, 423
- Nickel-based alloys, 413
- Nitrogen, 389, 394, 395, 396, 397
- Nitrogen-assisted cutting, 395, 398
- Nitrogen cuts, 398
- Nominal ocular hazard distance (NOHD), 209
- Non-contact sensors, 298
- Non-metals, 391, 397, 399
- Notch effect, 527
- Nozzle, 328, 391, 393–394, 407, 408
- Nozzle angle, 310
- Nozzle's orientation, 310
- Nozzle parameters, 311
- Nozzle stand-off distance, 393, 408
- Numerical aperture, 128

- Offline programming, 330
- Offset, 322–323
- On-line process control, 374
- Operation temperature, 35, 36
- Optical characteristics, 49–53
- Optical gain, 7–11
- Optical losses, 58
- Optical-path rotating devices, 168

- Optical penetration depth, 363, 364, 375, 376, 383, 385
- Optical power, 34
- Optical power density, 20
- Optical properties, 375, 376
- Optical resonator, 11–12
- Optical stacking, 149
- Optimization, of wall plug efficiency, 23
- Organic coating, 346
- Organic materials, 396
- Out-gassing gap, 327
- Output power, 391
- Overheating, 377
- Overlap joint, 346, 363, 364, 383
- Overlap welding, 335, 378, 381
- Oxidation, 311, 312, 389, 441, 449, 480, 503
- Oxide layer, 323, 324
- Oxides, 323, 389, 391
- Oxygen, 388, 391, 394, 396, 398, 405, 406, 407, 408
- Oxygen cutting, 389, 398
 - applications, 407
 - variants, 405
- Oxygen jet, 406, 407
- Oxygen pressure, 408, 410
- Oxygen purity, 408

- PA (Polyamide), 382, 383, 385, 386
- Packaging-induced stress, 43
- Packaging process, 75
- Pack of fibers, 386
- Paper, 389, 396, 397, 398
- Parameter extraction, 22
- Partially crystalline polymers, 379
- Particle-reinforced metals, 413
- Passivating scales, 406
- Pasteboard, 396, 397, 398, 403, 404
- Patterning, 29
- PC (Polycarbonate), 373, 383
- Peclet number, 390
- Peltier module, 92, 93
- Perlite, 432
- Phase steel, 313
- Phase transition, 389, 400–401
- Photocurrent spectroscopy (PCS), 42, 112, 115
- Photo-elastic measurement method, 113
- Photo-elastic stress measurement, 109–111
- Photolithography, 28–29
- Photo-luminescence spectroscopy (PLS), 112

- Photoresists, 28
- P-I-characteristics (power vs. current), 49–50, 61, 69
- Pitch, 69, 137, 222, 227, 237, 252
- Plastics, 389, 391, 397, 399
- Plastification, 362, 363, 364
- Plate thickness, 405, 406, 407, 410
- Plumb, 342
- p-n-junction, 8
- Polarization, 51–52
 - coupling, 217, 225, 239
 - multiplexing, 126, 142–145
- Polyamide. *See* PA
- Polycarbonate. *See* PC
- Polypropylene. *See* PP
- Polymer welding, 258, 285, 375
- Positioning, of laser focal spot, 419
- Position sensors, 296
- Powder-feed, 490, 506
 - nozzles, 485
- Power balance, for laser cutting, 390
- Power demand, 391
- Power density, 285, 388
- Power density distribution, 186–188, 196–204, 338, 340
- PP (Polypropylene), 383
- PPJ (pick, place and join) process, 79, 80
- Precision parts, 334
- Preheating, 388, 406, 407, 434, 474, 492, 505
- Pressure measurement, 373
- Pressure drop, 98
- Pressure-wheel system, 294
- Prism stacks, 149, 224
- Process control, 427, 440, 462
- Process control system, 272–278
- Process diagnostic systems, 174
- Process forces, 419, 420, 421, 424
- Process gas, 312
- Processing center, 478
- Process monitoring, 371, 373, 440
- Process regimes, 287, 288
- Process temperature, 353, 390, 416
- Process tolerances, 316, 322–323
- Propagation, of beam widths, 188, 192–196
- Protective glass window, 418
- p-side-down assembly, 60
- p-side-up assembly, 253
- Pulsing, 391
- Pyrometer, 272, 275, 350, 416, 440, 464
- Pyrometer measurement, 372
 - of working temperature, 371
- Pyrometric signal, 354
- Pyrometry, 371
- Quality control, 371
- Quantum well, 9, 13, 15
 - compressively strained, 10–12, 52
 - tensile strained, 10–13
- Quasi-simultaneous welding, 367–368
- Radial annular welds, 321
- Raw beam diameter, 393
- Rayleigh length, 192, 389, 392, 393, 400, 409
- Reaction, 389
- Reaction power, 390, 391, 406
- Rearrangement, of beam shape, 386
- Reflectance, 381, 427
- Reflectivity, 61
- Reflow process, 79
- Reinforcement materials, 376
- Reliability, 53–55, 63, 64, 70
- Remelting, 433, 434, 503, 526
- Removal rate, 413
- Residual stress, 433, 493, 505, 506, 508
- Ridge waveguide structure, 16
- Ring-shaped laser, 278–283
- Robot, 388, 444, 475, 508
- Robot systems, 479
- Rollover, 20, 35
- Roof bow, 328–329
- Roof header, 328, 329, 330, 348, 349
- Rosenthal solution, 402–403
- Rough-down process, 415
- Roughing, 424
- Roughness, 398, 430, 434, 462, 515
- Running costs, 399
- Safety, 209–210
- Scanner, 405
- Scanning, 367–368
- Scattering, 375, 376, 378, 379
- Scheimpflug condition, 298–299
- Schematic, of tapered diode laser, 57
- Seam cross-section, 346
- Seam strength versus energy input per unit length, 377
- Segmented mirrors, 149
- Self-focusing, 57
- Self-quenching, 434, 475, 480
- Separation, 402
- Separation process, 401
- Series resistance, 34

- Shack–Hartmann sensor, 205
- Sheet thickness, 392, 394, 395
- Shielding gas, 293, 310, 311, 312, 314
- Short-term stability, 204
- Shrinkage, 376
- Silicon, 355, 356
- Simple astigmatic, 190
- Simulation, 338, 340, 402, 403
- Simultaneous tacking, 384
- Simultaneous welding, 257, 258, 368–370, 372, 373, 384–385, 386, 387
- Single-shot cutting, 388
- Single-shot cutting-to-length, 400, 401, 402, 404, 405
- Single-shot welding, 290, 314–315
- Single-wheel system, 295
- Slit-shaped nozzle, 401
- Slope efficiency, 17, 34, 85
- Slow-axis, 37, 53, 306, 309, 316, 318, 323
- Slow-axis collimation, 135–138
- Smile, 79, 103, 131, 133, 135, 159, 220, 257
- Softening, 419
- Softening zone, 380, 381
- Solder depot, 359
- Soldering, 78, 246, 257, 285, 349, 350, 352, 353, 355, 356, 357, 358, 360
- Solder interface, 83
- Solder joint, 360
- Solder pad, 354, 357, 358, 359
- Solder thickness, 82
- Solidification, 355
- Spatial coupling, 147–149, 223, 239
- Spatial emission pattern, 52–53
- Spatial multiplexing, 125
- Spatters, 291, 292, 327, 328, 329
- Speckle pattern interferometry, 108
- Spectral broadening, 35
- Spherulites, 376
- Spindle, 417
- Spot, 389
- Spot orientation, 309, 317, 318, 319
- Spot welds, 314
- Square butt joints, 315
- Square butt welding, 316, 317
- Stacking, 121–178, 218, 262, 310
 - faults, 150, 153, 154, 170, 172
 - techniques of, 150–162
- Stainless steel, 286, 290, 304, 305, 306, 307, 309, 311, 312, 314, 315, 317, 319, 320, 321, 322–323, 339, 341, 389, 394, 395, 396, 398, 401, 402, 403, 404, 405
- Standard characterization methods, 33–40
- Standards, 181, 210–211
- Stellite, 421, 423
 - machining, 422
 - materials, 416
- Step mirrors, 168, 218
- Stigmatic, 190
- Strength, of joint, 318
- Stress, 82, 104, 105, 109, 111, 113, 114
- Stress distribution, 110
- Sublimation cutting, 389, 398
- Surface preparation, 382
- Surface temperature, 390, 432, 440
- Symmetric beam, 152
- Symmetrization, 162, 174
- Tactile seam tracking, 302–303
- Tailored blanks, 331, 332, 333
- Tapered devices, 56, 59–61
- Tapered diode laser, 56, 58, 62, 64, 65, 66, 67, 69, 164, 172, 233, 235–245
 - astigmatism of, 68
 - fabrication of, 59–61, 245
 - lifetime of, 63
 - reliability of, 63, 70
- Tapered diode laser bars, 233
- TE polarization, 51
- Tearing process, 402
- Tearing-up, 401
- Temperature distribution, 338, 339, 341, 350, 359, 413
- Temperature field, 419, 421
- Temperature measurement, 350
- Temperature profile, 354, 376, 413
- Tensile shear stress, 360, 361
- Tensile-strained QWs, 10, 11
- Tensile strength, 401, 402
- Terminal lead, 353, 354–355, 357, 358, 359, 360
- Thermal conductivity, 107, 287, 396
- Thermal diffusivity, 338, 390
- Thermal expansion coefficients, of
 - thermoplastics, 376
- Thermal expansion measurements, 114
- Thermal power, 84
- Thermal properties, of thermoplastics, 376
- Thermal resistance, 36, 84, 87, 88, 90, 97, 98, 101
- Thermal wavelength drift factor, 36
- Thermo-electric cooling, 87, 92
- Thermo-mechanical stress cycles, 55
- Thermoplastics, 362
- Thick-film, 357

- Thin film polarizers, 142, 143, 144
- Thin metal sheets, 399
- Three-dimensional cutting, 388
- Threshold current, 18, 34, 85
- Threshold current density, 17, 19
- Titanium, 391, 421
- TM polarization, 51
- Tool contact, 419
 - conditions, 420
- Tool diameter, 415
- Tool inserts, 425
- Tool length, 415
- Tool life, 412
- Tool materials, 422
- Tool service life, 420
- Tool wear, 412, 421, 422, 424, 425
- Top-hat distribution, 230, 225, 266, 273
- Total contact, 420
- Trailing nozzle, 311
- Transformation, 124, 390
- Transformation hardening, 272
- Transmission, 378, 379
- Transmission welding, 285
- Transmissive soldering, 355
- Transmittance, 427
- Transparency, 370
- Transparency current density, 19
- Transverse electric (TE), 12
- Transverse magnetic (TM), 12
- Triangulation, 299, 300
- Tube joints, 321
- Tubes, 333
- Tube-sheet joints, 320
- Turbo charger, 520

- Undercut, 315, 327
- Unsoldering, 355
- UV curable adhesives, 118
- UV curable glue, 156

- Valence bond, 6
- Valve seats, 467, 506, 518
- Vapor capillary, 288, 289, 340
- Vapor gradient, 394
- Vaporization, 394
- Vaporization cutting, 389, 391
- Vaporization temperature, 338
- Vaporizing, 388
- Vapor plume, 288, 289, 311, 312, 315, 326

- Vertical waveguide structure, 12–14
- Vicat softening temperature, 380
- Viscosity of plastified (molten)
 - thermoplastics, 376
- Voltage, 34

- Wall plug efficiency, 20, 24, 25, 49–50, 61, 69
- Wavefront, 194
 - of laser beam, 205
- Waveguide, 12, 164
- Wavelength coupling, 225, 235, 238, 239, 279
- Wavelength distribution, 51
- Wavelength multiplexing, 126, 145–147
- Wavelength spectrum, 35
- Weibull analysis, 207
- Welding, 285
 - of aluminum, 287
 - depth, 304, 305, 306, 307, 308, 309, 312, 322
 - head, 294, 295
 - sequence, 328, 329
 - strength, 385
 - structure, 313–314
- Wetting, 346, 354–355
- Wetting angle, 342
- Wetting temperature, 354
- Widths, of power density distribution, 187, 188, 201–203
- Wigner distribution, 184–185
- Wire, 337, 338
- Wire cladding, 408, 489, 525
- Wire feeder, 345
- Wire feed rate, 346
- Woehler diagram, 208
- Wood, 389, 399
- Working area, 418
- Working distance, 291, 292, 316, 322, 325, 353
- Working-spot size, 388

- Young's modulus, 104

- Zementite, 432
- Zinc-coating, 327, 329, 342
 - of steel, 292, 296
- Zinced mild steel, 397

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